

STGW10M65DF2

Trench gate field-stop IGBT, M series 650 V, 10 A low-loss in TO-247 package

Datasheet - production data

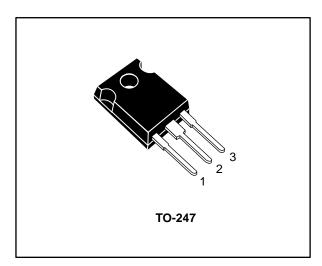
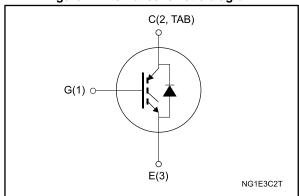


Figure 1: Internal schematic diagram



Features

- 6 µs of short-circuit withstand time
- V_{CE(sat)} = 1.55 V (typ.) @ I_C = 10 A
- Tight parameter distribution
- Safer paralleling
- Positive V_{CE(sat)} temperature coefficient
- Low thermal resistance
- Soft and very fast recovery antiparallel diode
- Maximum junction temperature: T_J = 175 °C

Applications

- Motor control
- UPS
- PFC
- General purpose inverter

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the M series IGBTs, which represent an optimal balance between inverter system performance and efficiency where low-loss and short-circuit functionality are essential. Furthermore, the positive $V_{\text{CE(sat)}}$ temperature coefficient and tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGW10M65DF2	G10M65DF2	TO-247	Tube

Contents STGW10M65DF2

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STGW10M65DF2 Electrical ratings

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
Vces	Collector-emitter voltage (V _{GE} = 0 V)	650	V
1.	Continuous collector current at T _C = 25 °C	20	А
lc	Continuous collector current at T _C = 100 °C	10	A
ICP ⁽¹⁾	Pulsed collector current	40	Α
V_{GE}	Gate-emitter voltage	±20	V
l _F	Continuous forward current at T _C = 25 °C	20	Α
IF	Continuous forward current at T _C = 100 °C	10	A
I _{FP} ⁽¹⁾	Pulsed forward current	40	Α
Ртот	Total dissipation at T _C = 25 °C	115	W
T _{STG}	Storage temperature range	- 55 to 150	°C
TJ	Operating junction temperature range - 55 to 175		C

Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
RthJC	Thermal resistance junction-case IGBT	1.3	
RthJC	Thermal resistance junction-case diode	2.08	°C/W
RthJA	Thermal resistance junction-ambient	50	

 $[\]ensuremath{^{(1)}}\mbox{Pulse}$ width limited by maximum junction temperature.

Electrical characteristics STGW10M65DF2

2 Electrical characteristics

 $T_C = 25$ °C unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu\text{A}$	650			V
		V _{GE} = 15 V, I _C = 10 A		1.55	2.0	
V _{CE(sat)}	V _{CE(sat)} Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 10 A, T _J = 125 °C		1.9		V
		V _{GE} = 15 V, I _C = 10 A, T _J = 175 °C		2.1		
		I _F = 10 A		1.5	2.25	
V _F	Forward on-voltage	I _F = 10 A, T _J = 125 °C		1.3		V
		I _F = 10 A, T _J = 175 °C		1.2		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 250 \mu A$	5	6	7	V
ICES	Collector cut-off current	V _{GE} = 0 V, V _{CE} = 650 V			25	μΑ
I _{GES}	Gate-emitter leakage current	Vce = 0 V, VgE = ± 20 V			±250	μΑ

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Cies	Input capacitance		-	840	-	
Coes	Output capacitance	V _{CE} = 25 V, f = 1 MHz,	-	63	-	pF
Cres	Reverse transfer capacitance	V _{GE} = 0 V	1	16	1	μ.
Qg	Total gate charge	Vcc = 520 V, Ic = 10 A,	ı	28	1	
Qge	Gate-emitter charge	V _{GE} = 0 to 15 V (see <i>Figure 30: " Gate charge</i>	-	6	-	nC
Q_{gc}	Gate-collector charge	test circuit")	-	12	-	

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time			19	-	ns
tr	Current rise time			7.4	-	ns
(di/dt) _{on}	Turn-on current slope	V _{CE} = 400 V, I _C = 10 A,		1086	-	A/µs
t _{d(off)}	Turn-off-delay time	$V_{GE} = 400 \text{ V}, 10 = 10 \text{ A},$ $V_{GE} = 15 \text{ V}, R_{G} = 22 \Omega$		91	-	ns
t _f	Current fall time	(see Figure 29: " Test circuit		92	1	ns
E _{on} ⁽¹⁾	Turn-on switching energy	for inductive load switching")		0.12	-	mJ
E _{off} (2)	Turn-off switching energy			0.27	-	mJ
Ets	Total switching energy			0.39	-	mJ
t _{d(on)}	Turn-on delay time			18	-	ns
tr	Current rise time			9	-	ns
(di/dt) _{on}	Turn-on current slope	V _{CE} = 400 V, I _C = 10 A,		890	-	A/µs
t _{d(off)}	Turn-off-delay time	$V_{GE} = 15 \text{ V}, R_{G} = 22 \Omega$		90	-	ns
tf	Current fall time	T _J = 175 °C (see <i>Figure 29: " Test circuit</i>		170	-	ns
E _{on} ⁽¹⁾	Turn-on switching energy	for inductive load switching")		0.26	-	mJ
E _{off} (2)	Turn-off switching energy			0.4	-	mJ
E _{ts}	Total switching energy			0.66	1	mJ
	Chart aircuit withotond time	V _{CC} ≤ 400 V, V _{GE} = 13 V, T _{Jstart} = 150 °C	10		-	
t _{sc}	Short-circuit withstand time	Nort-circuit withstand time $V_{CC} \le 400 \text{ V}, V_{GE} = 15 \text{ V}, \\ T_{Jstart} = 150 \text{ °C}$	6		-	μs

Notes:

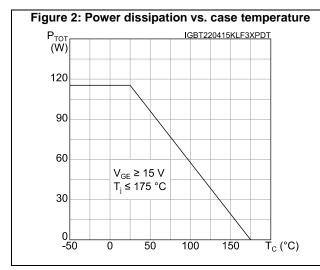
Table 7: Diode switching characteristics (inductive load)

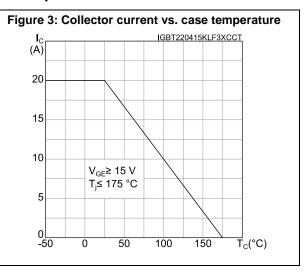
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{rr}	Reverse recovery time		ı	96	-	ns
Q_{rr}	Reverse recovery charge	$I_F = 10 \text{ A}, V_R = 400 \text{ V},$	-	373		nC
Irrm	Reverse recovery current	V _{GE} = 15 V, di/dt = 1000 A/µs	ı	13	-	Α
dl _{rr} /dt	Peak rate of fall of reverse recovery current during t _b	(see Figure 29: " Test circuit for inductive load switching")	ı	661	ı	A/µs
Err	Reverse recovery energy		ı	52	ı	μJ
t _{rr}	Reverse recovery time	1 40 4 1/ 400 1/	ı	201	ı	ns
Qrr	Reverse recovery charge	$I_F = 10 \text{ A}, V_R = 400 \text{ V},$ $V_{GE} = 15 \text{ V}.$	ı	1352	ı	nC
I _{rrm}	Reverse recovery current	di/dt = 1000 A/μs,	-	19	-	Α
dl _{rr} /dt	Peak rate of fall of reverse recovery current during t _b	T _J = 175 °C (see Figure 29: " Test circuit for inductive load switching")	ı	405	ı	A/µs
Err	Reverse recovery energy	Tor madelive load switching	1	150	-	μJ

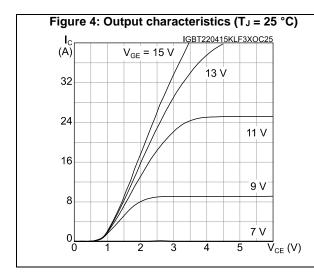
⁽¹⁾Including the reverse recovery of the diode.

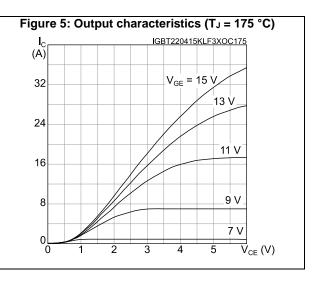
 $[\]ensuremath{^{(2)}}\mbox{Including}$ the tail of the collector current.

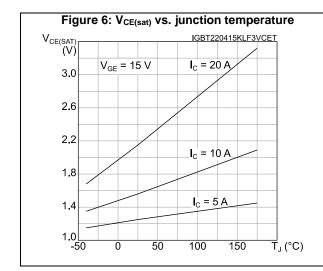
2.1 Electrical characteristics (curves)

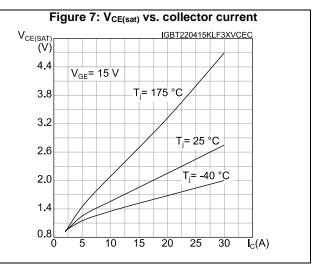


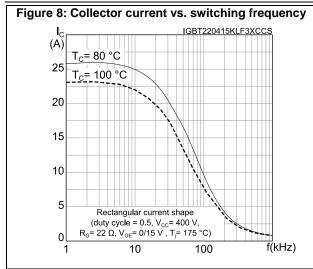


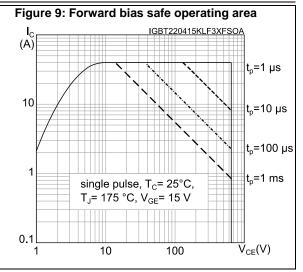


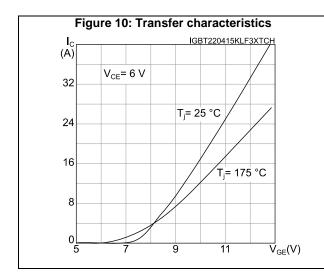


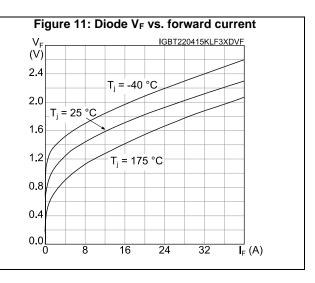


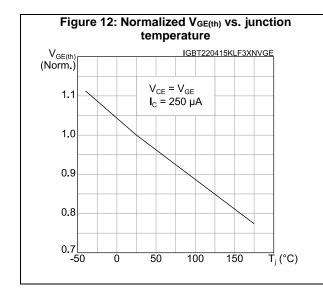


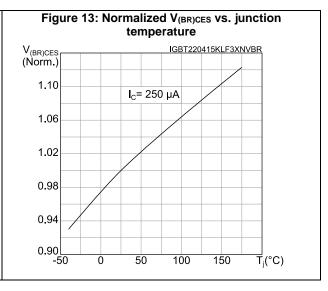


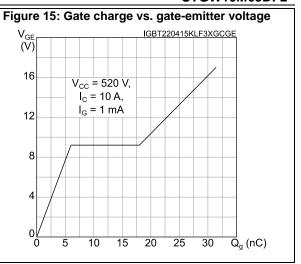


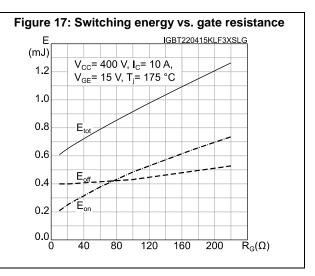


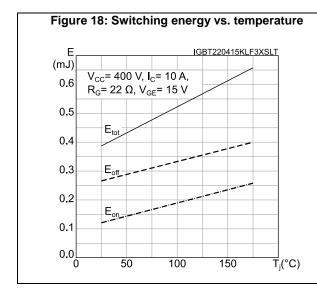


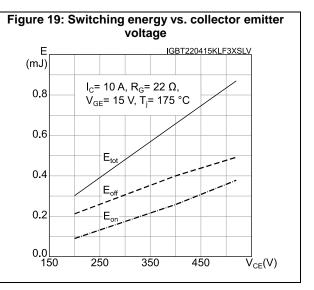






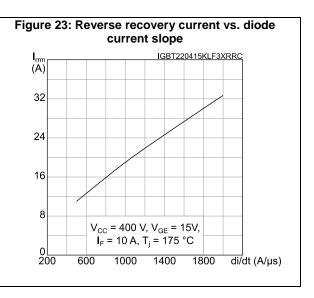


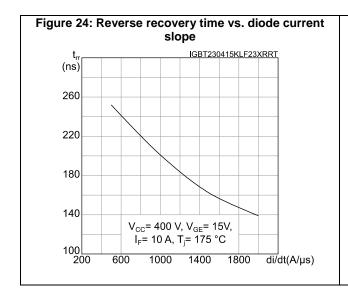


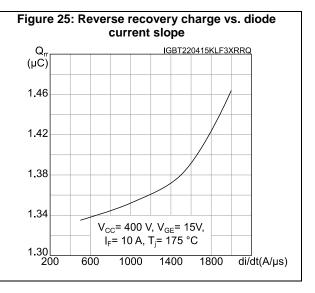


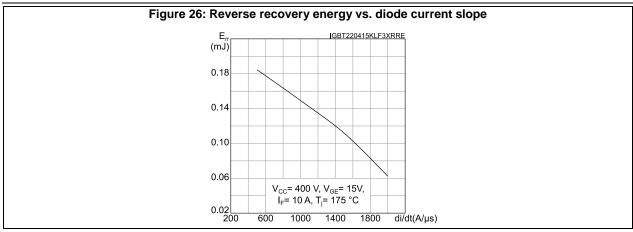
STGW10M65DF2 Electrical characteristics

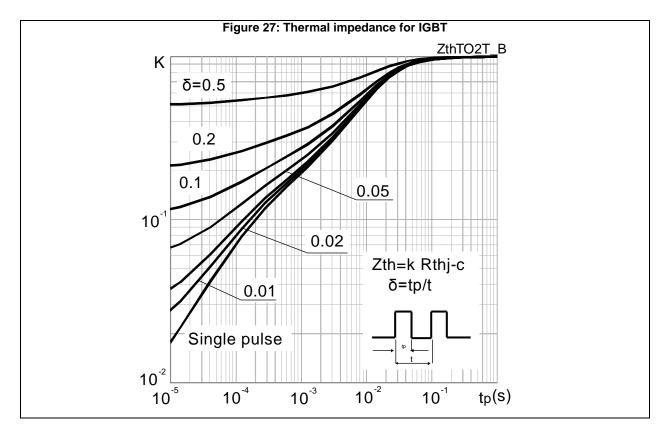
Figure 20: Short-circuit time and current vs. VGE ne anu Carlos IGBT220415KLF3XSCV ISC (A) V_{CC}≤ 400 V T_i≤ 150 °C sc 9 $\overline{V}_{GE}(V)$

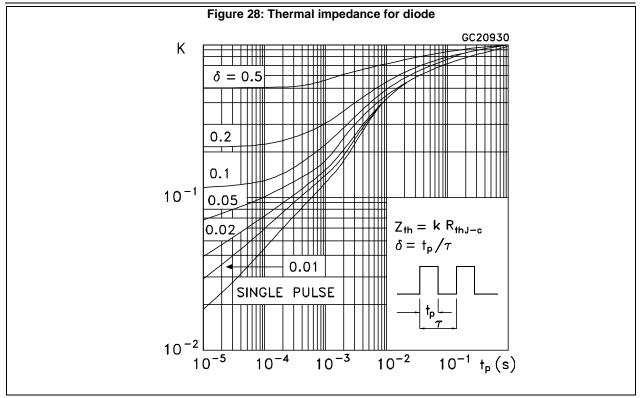






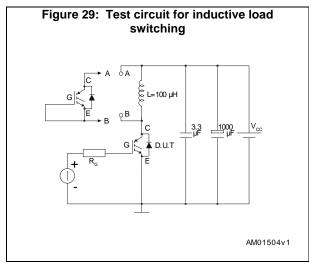


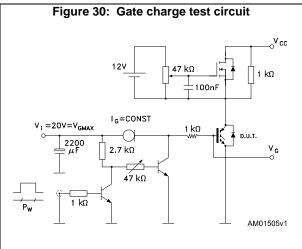


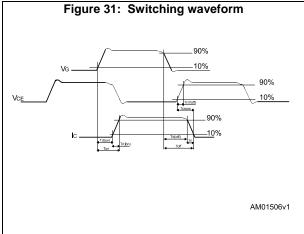


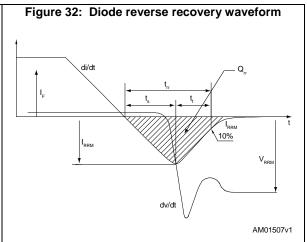
Test circuits STGW10M65DF2

3 Test circuits









4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

4.1 TO-247 package information

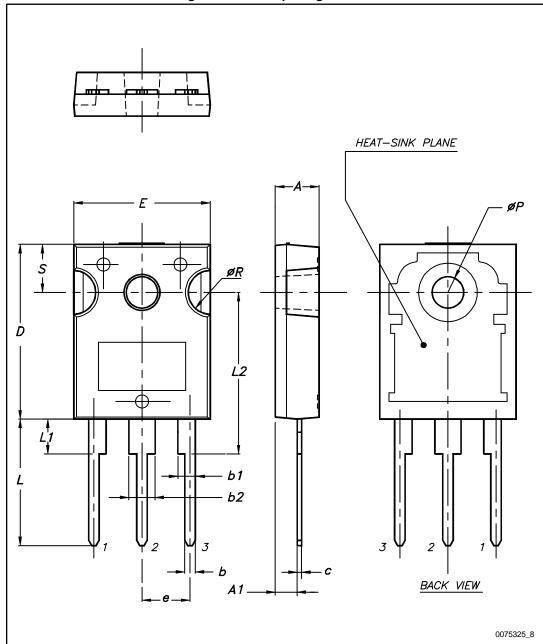


Figure 33: TO-247 package outline

Table 8: TO-247 package mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
С	0.40		0.80
D	19.85		20.15
Е	15.45		15.75
е	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

STGW10M65DF2 Revision history

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
08-Mar-2016	1	First release.
07-Apr-2017	2	Modified title, features and applications on cover page Modified Table 2: "Absolute maximum ratings", Table 4: "Static characteristics" and Table 7: "Diode switching characteristics (inductive load)" Minor text changes.

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